



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Elisabetta Cilento	Representative Title	IBP Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STW82100BGAJ-2C	D562*W820GAJ, D562*W821GAJ, D562*W822GAJ, D562*W823GAJ	A	9998	2014-07-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	136.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7x1.0	44	flat	
Comment	62 VQFPN2 7x7x1.0 44 PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true

QueryList : REACH-16th December 2013

Query	Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true

Material Composition Declaration						Mfr Item Name	D562*W820GAJ, D562*W821GAJ, D562*W822GAJ, D562*W823GAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	6.284	mg	supplier	DIE	Silicon (Si)	7440-21-3		6284.000	mg	1000000	46206
LEADFRAME	Copper and its alloy	74.127	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		70874.000	mg	956116	521129
LEADFRAME				supplier	ALLOY	Iron (Fe)	7439-89-6		1709.000	mg	23055	12566
LEADFRAME				supplier	ALLOY	Phosphorus (P)	7723-14-0		0,06	mg	809	441
LEADFRAME				supplier	ALLOY	Zinc (Zn)	7440-66-6		0,091	mg	1228	669
LEADFRAME				supplier	COATING	Silver (Ag)	7440-22-4		1393.000	mg	18792	10243
DIE ATTACH	Other organic materials	1.269	mg	supplier	GLUE	Silver (Ag)	7440-22-4		0,976	mg	769110	7176
DIE ATTACH				supplier	GLUE	Epoxy resin A	9003-36-5		0,089	mg	70134	654
DIE ATTACH				supplier	GLUE	Epoxy resin B	Proprietary		0,051	mg	40189	375
DIE ATTACH				supplier	GLUE	Lactone	96-48-0		0,051	mg	40189	375
DIE ATTACH				supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0,051	mg	40189	375
DIE ATTACH				supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0,051	mg	40189	375
BONDING WIRE	Other inorganic materials	1.255	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1255.000	mg	1000000	9228
ENCAPSULATION	Other organic materials	50.556	mg	supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		4,55	mg	89999	33456
ENCAPSULATION				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		42467.000	mg	839999	312255
ENCAPSULATION				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		3286.000	mg	64997	24162
ENCAPSULATION				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0,253	mg	5004	1860
FINISHING	Other organic materials	2.510	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		2,51	mg	1000000	18456